

# MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS

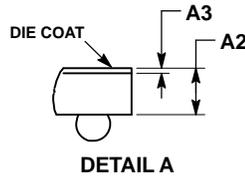
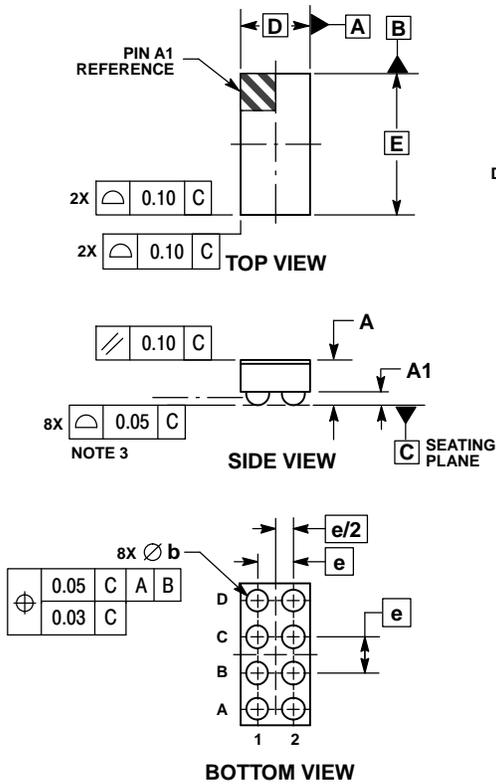
ON Semiconductor®



SCALE 4:1

WLCSP8, 1.57x0.77  
CASE 499BQ  
ISSUE A

DATE 01 SEP 2015

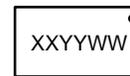


**NOTES:**

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. COPLANARITY APPLIES TO SPHERICAL CROWNS OF SOLDER BALLS.

| DIM | MILLIMETERS |      |
|-----|-------------|------|
|     | MIN         | MAX  |
| A   | ---         | 0.50 |
| A1  | 0.13        | 0.17 |
| A2  | 0.30 REF    |      |
| A3  | 0.025 BSC   |      |
| b   | 0.21        | 0.25 |
| D   | 0.77 BSC    |      |
| E   | 1.57 BSC    |      |
| e   | 0.40 BSC    |      |

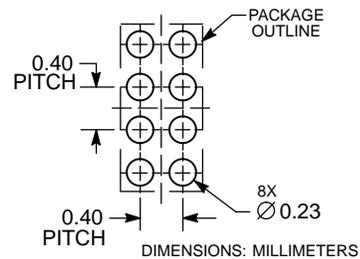
**GENERIC MARKING DIAGRAM\***



XX = Specific Device Code  
 YY = Year  
 WW = Work Week

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present.

**RECOMMENDED SOLDERING FOOTPRINT\***



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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| <b>STATUS:</b>          | ON SEMICONDUCTOR STANDARD |  |
| <b>NEW STANDARD:</b>    |                           |  |
| <b>DESCRIPTION:</b>     | WLCSP8, 1.57X0.77         | <b>PAGE 1 OF 2</b>   |

